



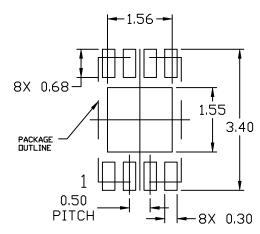
UDFN8 2x3, 0.5P CASE 517DH **ISSUE A**

DATE 10 DEC 2020

NOTES:

- DIMENSIONING AND TOLERANCING PER ASME
- THE TERMINAL TIPE TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

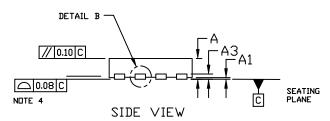
	MILLIMETERS			
DIM	MIN.	N□M.	MAX.	
Α	0.45	0.50	0.55	
A1	0.00		0.05	
A3	0.13 REF			
b	0.20	0.25	0.30	
D	1.90	2.00	2.10	
D2	1.30	1.40	1.50	
Ε	2.90	3.00	3.10	
E2	1.30	1.40	1.50	
е	0.50 BSC			
K	0.40 REF			
L	0.30	0.40	0.50	

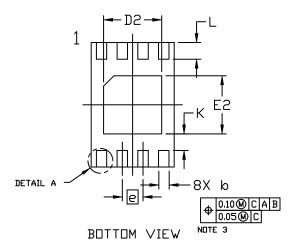


RECOMMENDED MOUNTING FOOTPRINT* For additional information on our Pb-Free strategy and soldering details, please download the DN Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

		1	B
PIN ONE — INDICATOR	/////		- E

TOP VIEW





GENERIC						
MARKING DIAGRAM						

XXXXX AWLYW= XXXXX = Specific Device Code

= Assembly Location Α

WL = Wafer Lot Υ = Year

W = Work Week = Pb-Free Package *This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	UDFN8 2X3, 0.5P		PAGE 1 OF 1	

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